

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2466	257/690	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 18:28
L3	3686	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 18:39
L4	1107	257/776	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 19:05
L5	260	257/798	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 19:16
L6	1465	257/303	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 19:45
L7	2523	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 19:17
L8	2220	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 19:48
L9	2497	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 19:51

L10	517	257/621	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:17
L11	3133	174/261	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:21
L12	2270	438/612	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:43
L13	3	257/E23.078	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:44
L14	2	257/E33.066	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:44
L15	0	257/E21.537	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:44
L16	1	257/E21.538	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:45
L17	2	257/E21.588	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 20:45
S1	0	(semiconductor or die or chip or IC) and (via or hole or open\$3) with pad same (via or hole or open\$3) with semicircle	USPAT	OR	OFF	2005/04/26 15:21

S3	87	(semiconductor or die or chip or IC) and (via or hole or open\$3) with semicircle	USPAT; JPO	OR	OFF	2005/04/26 15:30
S4	36875	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape	USPAT; JPO	OR	OFF	2005/04/26 15:31
S5	2	(semiconductor or die or chip or IC) and (via or hole or open\$3) with circule	USPAT; JPO	OR	OFF	2005/04/26 15:31
S6	3605	(semiconductor or die or chip or IC) and (via or hole or open\$3) with circle	USPAT; JPO	OR	OFF	2005/04/26 15:31
S7	75	(semiconductor or die or chip or IC) and (via or hole or open\$3) with semi-circle	USPAT; JPO	OR	OFF	2005/04/26 15:35
S8	3875	(semiconductor or die or chip or IC) and (via or hole or open\$3) with arc	USPAT; JPO	OR	OFF	2005/04/26 15:35
S9	1086	(semiconductor or die or chip or IC) and (via or hole or open\$3) with (pad or electrode or terminal or contact) with arc	USPAT; JPO	OR	ON	2005/04/26 15:35
S10	534	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape with arc	USPAT; JPO	OR	ON	2005/04/26 16:12
S11	219	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape with ellipse	USPAT; JPO	OR	ON	2005/04/26 16:48
S12	47549	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape	USPAT; JPO	OR	ON	2005/04/26 17:37
S13	905	(semiconductor or die or chip or IC) and (via or hole or open\$3) with shape with circle	USPAT; JPO	OR	ON	2005/04/26 16:49
S14	1	"4188438".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S15	1	"4661375".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S16	1	"5084752".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S17	1	"5134460".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S18	1	"5470787".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:27
S19	1	"4686538".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S20	1	"5359351".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28

S21	1	"5359351".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S22	1	"6037957".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S23	1	"6071427".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:28
S24	1	"6123410".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:29
S25	1	"5939790".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:29
S26	1	"5986343".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:31
S27	1	"6229221".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:31
S28	1	"20010010408".PN.	US-PGPUB	OR	OFF	2005/04/26 17:32
S29	2	"D208222".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:32
S30	2	"0211011".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:32
S31	1	"D263563".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:32
S32	1	"3567844".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S33	1	"5513076".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S34	1	"6031283".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S35	1	"6106923".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:33
S36	1	"6166441".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:35
S37	1	"6175158".PN..	USPAT; USOCR	OR	OFF	2005/04/26 17:35
S38	1	"6201707".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:36
S39	1	"4609986".PN.	USPAT; USOCR	OR	OFF	2005/04/26 17:37
S40	251	S12 and 257/690	USPAT; JPO	OR	ON	2005/04/26 18:16
S41	1152	S12 and (257/774 or 257/776 or 257/798 or 228/180.22 or 257/303 or 257/784)	USPAT; JPO	OR	ON	2005/04/26 19:03

S42	2285	257/690	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 17:47
S43	3401	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 20:41
S44	1038	257/776	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:43
S45	77	(semiconductor or die or chip or IC) and (via or hole or open\$3) with semicircle	USPAT	OR	OFF	2005/04/26 21:45
S46	47	(semiconductor or die or chip or IC) and (via or hole or open\$3) with (semicircle or semi-circle) with shape	USPAT	OR	OFF	2005/04/26 21:47
S47	5	(semiconductor or die or chip or IC) same (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle) with shape	USPAT	OR	OFF	2005/04/26 21:47
S48	19	(semiconductor or die or chip or IC) same (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle) with shape	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/12 16:33
S49	215	silicone near oxide with inorganic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:18
S50	29	silicone near oxide with inorganic near material	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:18

S51	243	257/798	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:44
S52	1367	257/303	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 22:58
S53	2334	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 23:04
S54	1918	228/180.22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 23:04
S55	8274	(semiconductor or die or dice or chip or IC) and pad with shape	USPAT; JPO	OR	ON	2005/10/11 18:44
S56	199	(semiconductor or die or dice or chip or IC) and pad with shap\$3 same (semi near circle or semicircle or arc or arch or semi-circle or semi-ellipse or ellipse)	USPAT; JPO	OR	ON	2005/10/11 19:28
S57	2	(semiconductor or die or dice or chip or IC) and pad with shap\$3 same (eclips\$3)	USPAT; JPO	OR	ON	2005/10/11 19:14
S58	48	(semiconductor or die or dice or chip or IC) and pad with shap\$3 same (cover\$3 with arc or arch)	USPAT; JPO	OR	ON	2005/10/11 19:14
S59	1	"5394011".PN.	USPAT; USOCR	OR	OFF	2005/10/11 19:17
S60	1	"5784262".PN.	USPAT; USOCR	OR	OFF	2005/10/11 19:18
S61	171	(semiconductor or die or dice or chip or IC) and pad with shap\$3 same (semi near circle or semicircle or arc or arch or semi-circle or moon)	USPAT; JPO	OR	ON	2005/10/11 19:20
S62	10	S61 not S56	USPAT; JPO	OR	ON	2005/10/11 19:20

S63	30	(semiconductor or die or dice or chip or IC) and pad with shap\$3 same (crescent or moon)	USPAT; JPO	OR	ON	2005/10/11 19:34
S64	5	(semiconductor or die or dice or chip or IC) same pad with shap\$3 same (crescent or moon)	USPAT; JPO	OR	ON	2005/10/11 19:35
S65	16	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal) with shap\$3 same (crescent or moon)	USPAT; JPO	OR	ON	2005/10/11 19:38
S66	131	(semiconductor or die or dice or chip or IC) and (pad or contact or terminal) with shap\$3 same (crescent or moon)	USPAT; JPO	OR	ON	2005/10/11 19:43
S67	101	S66 not S63	USPAT; JPO	OR	ON	2005/10/11 19:38
S68	41	(semiconductor or die or dice or chip or IC) same (pad) same (crescent or moon)	USPAT; JPO	OR	ON	2005/10/11 19:43
S69	41	(semiconductor or die or dice or chip or IC) same (pad) same (crescent\$3 or moon)	USPAT; JPO	OR	ON	2005/10/11 19:51
S70	15	(semiconductor or die or dice or chip or IC) same (pad) with (shap\$3 or form\$3) same (crescent\$3 or moon)	USPAT; JPO	OR	ON	2005/10/11 19:55
S71	129	(semiconductor or die or dice or chip or IC) same (pad) with (shap\$3) same (crescent\$3 or convex or concave)	USPAT; JPO	OR	ON	2005/10/11 19:55
S72	91	(semiconductor or die or dice or chip or IC) same (pad) with (shap\$3) with (crescent\$3 or convex or concave)	USPAT; JPO	OR	ON	2005/10/11 20:14
S73	261277	(semiconductor or die or dice or chip or IC) same (pad) with (cover\$3) same shap\$3 (crescent\$3 or convex or concave)	USPAT; JPO	OR	ON	2005/10/11 20:15
S74	12	(semiconductor or die or dice or chip or IC) same (pad) with (cover\$3) same shap\$3 with (crescent\$3 or convex or concave)	USPAT; JPO	OR	ON	2005/10/11 20:17
S75	16	(semiconductor or die or dice or chip or IC) same (pad) with (cover\$3) same shap\$3 with (crescent\$3 or convex or concave or arc or arch)	USPAT; JPO	OR	ON	2005/10/11 20:17

S76	16	(semiconductor or die or dice or chip or IC) same (pad) with (cover\$3) same shap\$3 with (crescent\$3 or convex or concave or arc or arch\$3)	USPAT; JPO	OR	ON	2005/10/11 20:19
S77	213949	(semiconductor or die or dice or chip or IC) same (pad) shap\$3 with (crescent\$3 or convex or concave or arc or arch\$3)	USPAT; JPO	OR	ON	2005/10/11 20:20
S78	127	(semiconductor or die or dice or chip or IC) same (pad) with shap\$3 with (crescent\$3 or convex or concave or arc or arch\$3)	USPAT; JPO	OR	ON	2005/10/11 20:28
S79	7	(semiconductor or die or dice or chip or IC) same (pad) with open\$3 with shap\$3 with (crescent\$3 or convex or concave or arc or arch\$3)	USPAT; JPO	OR	ON	2005/10/11 20:29
S80	9	(semiconductor or die or dice or chip or IC) same (pad) with open\$3 with shap\$3 same (crescent\$3 or convex or concave)	USPAT; JPO	OR	ON	2005/10/11 20:30
S81	0	(semiconductor or die or dice or chip or IC) same (pad) with (open\$3 or via) with shap\$3 same (crescent\$3)	USPAT; JPO	OR	ON	2005/10/11 20:30
S82	1	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal) with (open\$3 or via) with shap\$3 same (crescent\$3)	USPAT; JPO	OR	ON	2005/10/11 20:31
S83	1	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal or electrode) with (open\$3 or via) with shap\$3 same (crescent\$3)	USPAT; JPO	OR	ON	2005/10/11 20:31
S84	1	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal or electrode) with (open\$3 or via) with shap\$3 same (crescent\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:31
S85	10	(semiconductor or die or dice or chip or IC) and (pad or contact or terminal or electrode) with (open\$3 or via) with shap\$3 same (crescent\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:33
S86	29	(semiconductor or die or dice or chip or IC) and (pad or contact or terminal or electrode) with (open\$3 or via) same shap\$3 with (crescent\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:37

S87	163	(semiconductor or die or dice or chip or IC) and (pad or contact or terminal or electrode) with shap\$3 with (crescent\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:49
S88	152	S87 not S86	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:37
S89	164	(semiconductor or die or dice or chip or IC) and (pad or contact or terminal or electrode) with shap\$3 with (crescent\$3 or quarter near moon)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:44
S90	12	S89 not S88	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:45
S91	2698	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal or electrode) with (open\$3 or hole or via) with (project\$3 or dent\$3 or indentat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:50
S92	314	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal or electrode) with (open\$3 or hole or via) with shap\$3 with (project\$3 or dent\$3 or indentat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/10/11 20:50
S93	161	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal or electrode) with (open\$3 or hole or via) with shap\$3 with (project\$3 or dent\$3 or indentat\$3)	USPAT	OR	ON	2005/10/11 21:09
S94	1	"3567844".PN.	USPAT; USOCR	OR	OFF	2005/10/11 20:52
S95	1	"5513076".PN.	USPAT; USOCR	OR	OFF	2005/10/11 20:55
S96	1	"6031283".PN.	USPAT; USOCR	OR	OFF	2005/10/11 20:55
S97	1	"6106923".PN.	USPAT; USOCR	OR	OFF	2005/10/11 20:55
S98	1	"6166441".PN.	USPAT; USOCR	OR	OFF	2005/10/11 20:56
S99	1	"6175158".PN.	USPAT; USOCR	OR	OFF	2005/10/11 20:57
S100	1	"6201707".PN.	USPAT; USOCR	OR	OFF	2005/10/11 20:57

S10 1	195	(semiconductor or die or dice or chip or IC) same (pad or contact or terminal or electrode) with shap\$3 with (arc or arch or moon)	USPAT	OR	ON	2005/10/11 21:27
S10 2	25	(semiconductor or die or dice or chip or IC) same (pad) with shap\$3 with (arc or arch or moon)	USPAT	OR	ON	2005/10/11 21:30
S10 3	1	"5394011".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:28
S10 4	1	"5784262".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:28
S10 5	39	(semiconductor or die or dice or chip or IC) same (pad) with shap\$3 with (arc or arch or moon or polygon)	USPAT	OR	ON	2005/10/11 21:43
S10 6	14	S105 not S102	USPAT	OR	ON	2005/10/11 21:36
S10 7	1	"5939790".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:34
S10 8	1	"5986343".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:34
S10 9	1	"6229221".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:34
S11 0	1	"20010010408".PN.	US-PGPUB	OR	OFF	2005/10/11 21:35
S11 1	2	"6417575"	USPAT	OR	ON	2005/10/11 21:36
S11 2	1	"5404047".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:40
S11 3	1	"5942800".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:40
S11 4	1	"6100589".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:40
S11 5	1	"6287950".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:41
S11 6	1	"6313540".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:41
S11 7	1	"6500748".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:41
S11 8	1	"6528881".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:41
S11 9	1	"6599578".PN.	USPAT; USOCR	OR	OFF	2005/10/11 21:42
S12 0	1	"20010010408".PN.	US-PGPUB	OR	OFF	2005/10/11 21:42

S12 1	4252	(semiconductor or die or dice or chip or IC) same (pad) with shap\$3	USPAT	OR	ON	2005/10/11 21:51
S12 2	102	(semiconductor or die or dice or chip or IC) same (pad) with shap\$3 with (arc or arch or moon or polygon or circle)	USPAT	OR	ON	2005/10/11 21:44
S12 3	63	S122 not S105	USPAT	OR	ON	2005/10/11 21:44
S12 4	2876	(semiconductor or die or dice or chip or IC) with (pad) with shap\$3	USPAT	OR	ON	2005/10/12 12:36
S12 5	1	"5468655".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:13
S12 6	1	"5578527".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:13
S12 7	1	"5846366".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:13
S12 8	1	"5955784".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:14
S12 9	1	"6066551".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:14
S13 0	1	"6144091".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:14
S13 1	1	"6201305".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:15
S13 2	1	"5327013".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:18
S13 3	1	"5977632".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:18
S13 4	1	"6222738".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:19
S13 5	1	"6291897".PN..	USPAT; USOCR	OR	OFF	2005/10/11 22:19
S13 6	1	"6324754".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:19
S13 7	1	"6444563".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:20
S13 8	1	"6627988".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:20
S13 9	1	"20020043726".PN.	US-PGPUB	OR	OFF	2005/10/11 22:20
S14 0	1	"20020089057".PN.	US-PGPUB	OR	OFF	2005/10/11 22:20
S14 1	1	"5615477".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:39

S14 2	1	"5936848".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:39
S14 3	1	"5962921".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:39
S14 4	1	"6046909".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:40
S14 5	1	"6086386".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:40
S14 6	1	"6140707".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:43
S14 7	1	"6180504".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:43
S14 8	1	"6187610".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:44
S14 9	1	"6194781".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:44
S15 0	1	"6232152".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:44
S15 1	1	"6232666".PN.	USPAT; USOCR	OR	OFF	2005/10/11 22:44
S15 2	1	"3778530".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:12
S15 3	1	"4605153".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:13
S15 4	1	"4851966".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:13
S15 5	1	"5196726".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:13
S15 6	2	"3339274".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:15
S15 7	2	"3461357".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:16
S15 8	1	"4151543".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:16
S15 9	1	"4857482".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:16
S16 0	1	"5014111".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:16
S16 1	1	"5196726".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:16
S16 2	1	"5311402".PN.	USPAT; USOCR	OR	OFF	2005/10/12 11:16
S16 3	4252	(semiconductor or die or dice or chip or IC) same (pad) with shap\$3	USPAT	OR	ON	2005/10/12 12:36

S16 4	2876	(semiconductor or die or dice or chip or IC) with (pad) with shape\$3	USPAT	OR	ON	2005/10/12 12:36
S16 5	1376	S163 not S164	USPAT	OR	ON	2005/10/12 14:43
S16 6	2007	228/180.22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 14:43
S16 7	1	"5216278".PN.	USPAT; USOCR	OR	OFF	2005/10/12 15:46
S16 8	1	"5468999".PN.	USPAT; USOCR	OR	OFF	2005/10/12 15:46
S16 9	1	"5583376".PN.	USPAT; USOCR	OR	OFF	2005/10/12 15:47
S17 0	1	"5591941".PN.	USPAT; USOCR	OR	OFF	2005/10/12 15:47
S17 1	1	"5637832".PN.	USPAT; USOCR	OR	OFF	2005/10/12 15:47
S17 2	1	"5637832".PN.	USPAT; USOCR	OR	OFF	2005/10/12 15:47
S17 3	1	"5706178".PN.	USPAT; USOCR	OR	OFF	2005/10/12 15:47
S17 4	0	(semiconductor or die or chip or IC) same pad with (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle) with shape	USPAT	OR	OFF	2005/10/12 16:34
S17 5	0	(semiconductor or die or chip or IC) same pad with (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle or semi near circle or semi-ellipse) with shape	USPAT; JPO	OR	OFF	2005/10/12 16:35
S17 6	0	(semiconductor or die or chip or IC) same pad with (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle or semi near circle or semi-ellipse or semi near ellipse or semiellipse) with shape	USPAT; JPO	OR	OFF	2005/10/12 16:35
S17 7	0	(semiconductor or die or chip or IC) same pad with (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle or semi near circle or semi-ellipse or semi near ellipse or semiellipse)	USPAT; JPO	OR	OFF	2005/10/12 16:35

S17 8	0	(semiconductor or die or chip or IC) and pad with (via or hole or open\$3 or recess or cavity or aperture) with (semicircle or semi-circle or semi near circle or semi-ellipse or semi near ellipse or semiellipse)	USPAT; JPO	OR	OFF	2005/10/12 16:35
S17 9	1	(semiconductor or die or chip or IC) and pad with (via or hole or open\$3 or recess or cavity or aperture) with shap\$3 same (semicircle or semi-circle or semi near circle or semi-ellipse or semi near ellipse or semiellipse)	USPAT; JPO	OR	OFF	2005/10/12 16:36
S18 0	1	(semiconductor or die or chip or IC) and pad with (via or hole or open\$3 or recess or cavity or aperture) same (semicircle or semi-circle or semi near circle or semi-ellipse or semi near ellipse or semiellipse)	USPAT; JPO	OR	OFF	2005/10/12 16:36
S18 1	64	(semiconductor or die or chip or IC) and (pad or contact or terminal) with (via or hole or open\$3 or recess or cavity or aperture) same (semicircle or semi-circle or semi near circle or semi-ellipse or semi near ellipse or semiellipse)	USPAT; JPO	OR	ON	2005/10/12 16:37
S18 2	9	(semiconductor or die or chip or IC) and (pad or contact or terminal) with (via or hole or open\$3 or recess or cavity or aperture) with shap\$3 same (semicircle or semi-circle or semi near circle or semi-ellipse or semi near ellipse or semiellipse)	USPAT; JPO	OR	ON	2005/10/12 16:39
S18 3	0	S182 not S181	USPAT; JPO	OR	ON	2005/10/12 16:39
S18 4	55	S181 not S182	USPAT; JPO	OR	ON	2005/10/12 16:39